

L Number	Hits	Search Text	DB	Time stamp
1	1	("5997175").PN.	USPAT; US-PGPUB	2003/08/02 08:15
2	1	("5881208").PN.	USPAT; US-PGPUB	2003/08/02 08:18
3	1	("5926742").PN.	USPAT; US-PGPUB	2003/08/02 08:18
4	430	((heating or cooling or annealing or RTP) and gas and (control\$3 with gas with (separately or selectively))) and @ad<20000317) and (wafer or substrate)	USPAT; US-PGPUB	2003/08/02 08:55
5	329	((heating or cooling or annealing or RTP) and gas and (control\$3 with gas with (separately or selectively))) and @ad<20000317) and (wafer or substrate)) and (gas with temperature)	USPAT; US-PGPUB	2003/08/02 08:28
6	12	((heating or cooling or annealing or RTP) and gas and (control\$3 with gas with (separately or selectively))) and @ad<20000317) and (wafer or substrate)) and ((gas with temperature) with (adjust or adjusting))	USPAT; US-PGPUB	2003/08/02 08:28
7	1	("5819684").PN.	USPAT; US-PGPUB	2003/08/02 08:51
8	1	("6300256").PN.	USPAT; US-PGPUB	2003/08/02 08:51
9	0	(controlling with gas with temperature) and (theraml with process) and @ad<20000317 and (wafer or substrate)	USPAT; US-PGPUB	2003/08/02 08:56
10	269	(controlling with gas with temperature) and (thermal with process) and @ad<20000317 and (wafer or substrate)	USPAT; US-PGPUB	2003/08/02 08:56